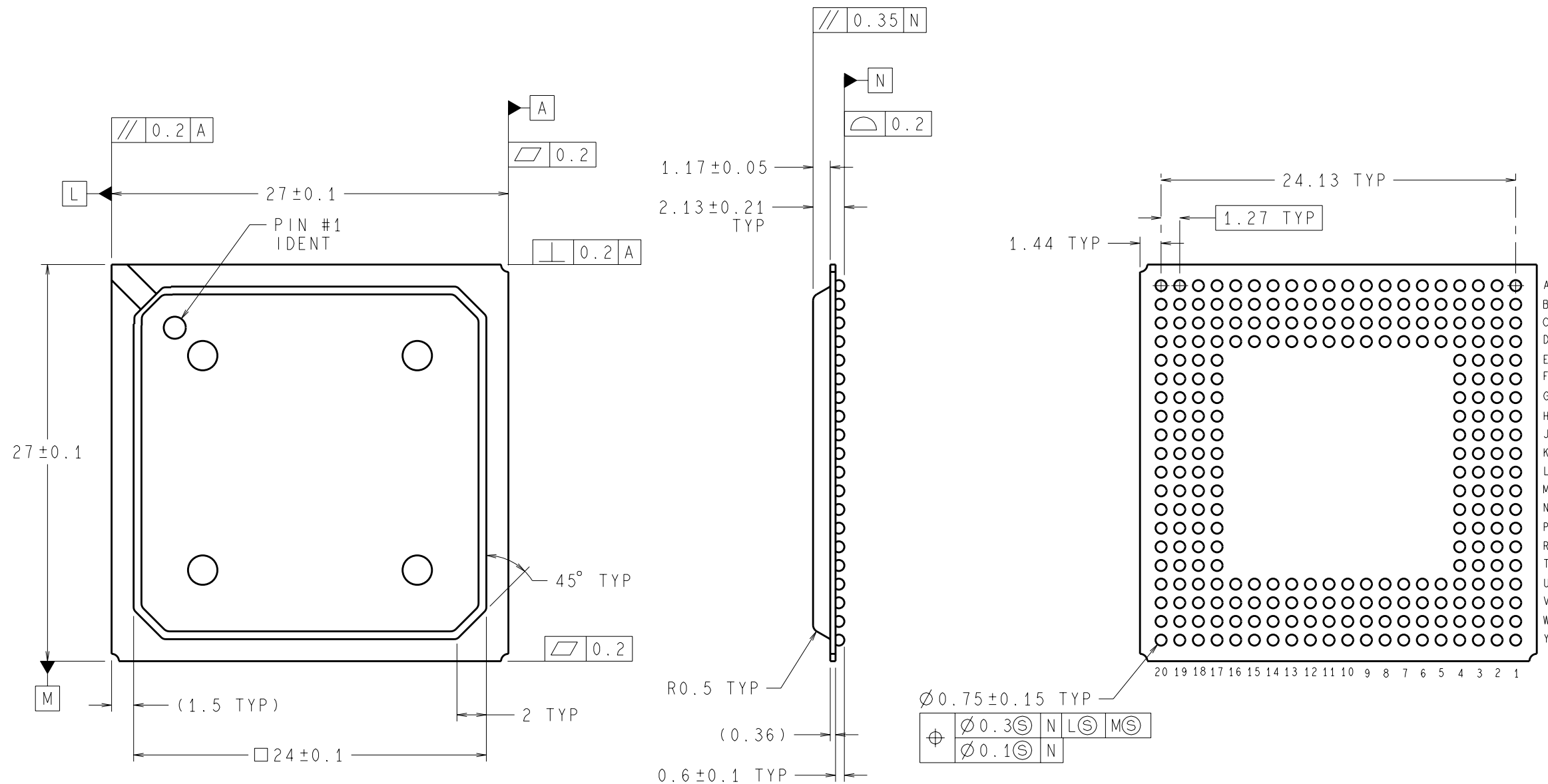


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10868	05/17/1995	DEG/SL
B	UPDATE DIM'S TO JEDEC STANDARD	11706	04/25/1997	TL/CP
C	UPDATE DIM. TOL'S & GEOM. TOL'S PER ECN; BALL DIA WAS 0.76±0.05.	326	07/13/2001	MS/VG



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- REFERENCE JEDEC REGISTRATION MO-151, VARIATION 1.27 PITCH.

APPROVALS		DATE	National Semiconductor		
DRAWN DE Grady		05/17/1995	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. THANH LEQUANG		07/13/2001	PBGA, 27 X 27 X 2.13mm, 256 BALL, 1.27mm PITCH		
ENGR. CHK. VIJAYLAXMI GUMASTE		07/13/2001			
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UBB256B	C
DO NOT SCALE DRAWING				SHEET 1 of 1	